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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 to 20 (canceled).

Claim 21 (currently amended): A device package, comprising:

a first wafer;

a second wafer;

a perimeter of ~~[[an]]~~ a first intermetallic mixture interposed between the first and the second wafers, the first intermetallic mixture comprising materials from a first reactive foil and a first bonding material, the first intermetallic mixture being formed after ~~[[an]]~~ a first exothermic reaction of the first reactive foil;

a device; and

a second intermetallic mixture interposed between the device and the first wafer, the second intermetallic mixture comprising materials from a second reactive foil and a second bonding material, the second intermetallic mixture being formed after a second exothermic reaction of the second reactive foil.

Claim 22 (currently amended): The device package of claim ~~[[20]]~~ 21, wherein the second wafer comprises a feature selected from the group consisting of a hole and a cavity.

Claim 23 (currently amended): A device package, comprising:

a first wafer;

a second wafer;

a perimeter of ~~[[an]]~~ a first intermetallic mixture interposed between the first and the second wafers, the first intermetallic mixture comprising materials from a first reactive foil and a first bonding material, the first intermetallic mixture being formed after ~~[[an]]~~ a first exothermic reaction of the first reactive foil;

a third wafer; and

a second perimeter of a second intermetallic mixture interposed between the second and the third wafers, the second intermetallic mixture comprising materials from a second reactive foil and a second bonding material, the second intermetallic

mixture being formed after a second exothermic reaction of the second reactive foil.

Claims 24 and 25 (canceled).

Claim 26 (currently amended): ~~[[A]] The device-wafer package of claim 23, further comprising:~~

~~a wafer having metal lines;~~

a device; and

~~[[an]] a third intermetallic mixture interposed between the device and the metal lines on the first wafer, the third intermetallic mixture bonding the device and the metal lines, the third intermetallic mixture comprising materials from a third reactive foil and a third bonding material, the third intermetallic mixture being formed after ~~[[an]]~~ a third exothermic reaction of the third reactive foil that releases heat to the bonding material.~~

Claim 27 (original): The package of claim 26, wherein the device is selected from the group consisting a MEMS (micro-electromechanical systems) device, an electronic device, and an optoelectronic device.

Claim 28 (new): The package of claim 21, wherein the second intermetallic mixture bonds the device to metal lines on the first wafer.

Claim 29 (new): The package of claim 28, wherein the device is selected from the group consisting a MEMS (micro-electromechanical systems) device, an electronic device, and an optoelectronic device.